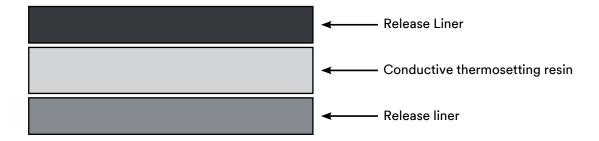


3M[™] Electrically Conductive Thermosetting Film 2201P

Product Description

3M[™] Electrically Conductive Thermosetting Film (C-TSF) 2201P is a specialty conductive thermosetting film with excellent adhesion to many substrates, good grounding performance and modest thermal bonding process conditions. 3M C-TSF 2201P was also numbered EAS-2201P (Electronic Assembly Solution = EAS) in its developmental phase.



Product Construction/Material Description

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

3M [™] Electrically Conductive Thermosetting Film 2201P		
Property	Value	
TSF Resin	Thermoset Epoxy / Acrylic Hybrid	
Conductive Fillers	Metallized (Ni/Cu/Ni) Polymeric (PET) Scrim Silver particles	
Approximate Thickness	Nominal < 0.065mm	
Construction	See diagram on page 1	

Typical Physical Properties and Performance Characteristics

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes. Final product specifications and testing methods will be outlined in the product's Certificate of Analysis (COA) that is provided once the product is approved by 3M for general commercialization and development work is completed.

3M [™] Electrically Conductive Thermosetting Film 2201P Grounding & Bonding*		
Peel Adhesion	Contact Resistance	
>50 oz/in (1420 g/in)*	<200 m-ohms**	

^{*}Tested using 3M test method on stainless steel. Results can vary based on bonding conditions and final overall sample thickness, backing type, substrate type, etc. Bonded samples evaluated after a nominal set of bonding conditions (30s @ 140-150°C bond line temperature and cool down @ 50psi). Peel adhesion at RT conditions after bonding. 90 degree peel adhesion.

^{**3}mm wide gold flex bonded with the 3M T-CSF 2201P onto a 1.25mm width gold trace on a standard FR4 PCB board (Nominal bond conditions @ 30s @ 140-150°C bond line temperature and cool down @ 50psi).

Maximum Operating Temperature Range***	85 – 95°C	3M Test Method
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^{***}The end use customer application, design & verification testing will determine the final in use effective temperature range based on each application's environmental conditions.

Application Guide

3M™ Electrically Conductive Thermosetting Film (C-TSF) 2201P is bonded using uniformly applied heat and pressure and a cooling delay under pressure to ensure a maximum end bond condition between substrates.

Tacking, or lightly bonding, the 3M C-TSF 2201P into position for final bond can be accomplished using the initial set-up conditions below. Each application may require a modification of conditions to meet each application specific needs.

Suggested TACKING Conditions (not a final bond)

- PSA level tack exists, no heat recommended for C-TSF
- 5-10 psi pressure

Suggested Bonding Conditions

- 145-155°C at the bond line temperature of the C-TSF 2201P
- 10-15 seconds dwell time
- 20-80 psi pressure
- Dwell under pressure until bond line cools to approximately < 93°C

Note: A Design of Experiments (DOE) is suggested to determine the optimum bonding conditions for each application. Actual application substrates, bonding equipment, bond line temperature, dwell times, end cooling temperature for a stable bond, etc. will vary with each design. Items for end user to test and evaluate include: peel adhesion, overlap shear, contact resistance, bond line squeeze-out of excess TSF resin, etc.

Temperatures noted for tacking and beginning bonding conditions guide are bond line temperatures. Actual bonding equipment surface temperatures will be higher based on equipment, process conditions and design substrates used to achieve the desired bond line temperatures. Dwell under pressure until bond line cools to approximately < 93°C may be another DOE items to be evaluated to see if a cooling down period is desired.

3M™ Electrically Conductive Thermosetting Film 2201P

3M™ Electrically Conductive Thermosetting Film (C-TSF) 2201P should be bonded under sufficient pressure-temperature-time such that the C-TSF has flowed and conductive members are well engaged to the substrate. The better the conductive members engage the substrate, typically the lower the contact resistance.

- Application should consider the flow properties of the C-TSF when considering the die cut size.
- Flow of the C-TSF can be used as an indication of proper bonding of an assembly (an indication of targeted pressure-temperature-time)
- C-TSF "flow" can be optimized for each application pressure-temperature-time with modified resin characteristics. Contact the 3M technical team for guidance.

Certificate of Analysis (COA)

The 3M Certificate of Analysis (COA) for this product is established when the product is commercially available from 3M. The commercially available product will have a COA specification established. The COA contains the 3M specifications and test methods for the products performance limits that the product will be supplied against. The 3M product is supplied to 3M COA test specifications and the COA test methods. Inquire with 3M for the COA for this product.

The TDS data contains preliminary data and is not the COA specification limits and/or test methods that may be used for COA purposes.

Final product specifications and testing methods will be outlined in the products Certificate of Analysis (COA) that is provided once the product is approved by 3M for general commercialization and development work is completed.

Storage and Shelf Life

The shelf life of 3M[™] Electrically Conductive Thermosetting Film (C-TSF) 2201P is 6 months from the 3M manufacture date when stored in original cartons/bags, in roll form, at 25°C (75°F) and protected from high humidity (>50% RH). After converting 3M C-TSF 2201P to the desired die cut shape, the film must be stored at no more than 25°C and kept bagged and protected from high humidity (>50% RH) to ensure a stable shelf life. High humidity environments can cause absorbed water in the film and lead to moisture volatilization that can produce bubbles during heat bonding.

It is possible to extend the shelf life of 3M C-TSF 2201P by up to six months if the film is stored in cold conditions at <2°C, protected from high humidity (>50% RH), and if the cold storage starts within 30 days of the manufacture date. The shelf life can be extended up to a maximum of 11 or 12 months from date of manufacture with the use of cold storage (<2°C) when stored in original cartons/bags, in roll form.



Safety Data Sheet: Consult Safety Data Sheet before use.

Regulatory: For regulatory information about this product, contact your 3M representative.

Technical Information: The technical information, recommendations and other statements contained in this document are based upon tests or experience that 3M believes are reliable, but the accuracy or completeness of such information is not guaranteed.

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Electronics Materials Solutions Division 3M Center, Building 224-3N-11 St. Paul, MN 55144-1000

Phone 1-800-251-8634 Fax 651-778-4244

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